

5 introducing a second agent comprising hydrogen peroxide [onto the] to a
6 metal [layer] plug.

9 (Amended) A method of removing at least one particle from a portion of a
metal layer on a substrate comprising:
depositing a slurry onto the substrate;
4 polishing the metal layer and the substrate; and
5 rinsing [the substrate] a metal plug with a solution comprising hydrogen
6 peroxide.

1 12. (Amended) The method of claim 9, wherein rinsing the [substrate] metal
2 plug occurs after polishing the metal layer and substrate.

1 13. (Amended) The method of claim 9, wherein rinsing the [substrate] metal
2 plug comprises rinsing with the solution which comprises approximately 4% by
3 volume or less of hydrogen peroxide.

14. The method of claim 9, wherein polishing the metal layer includes removing
2 the metal

18 (Amended) A method of polishing a metal layer on a substrate comprising:
polishing the metal layer and introducing a rinsing solution onto [the] a
metal [layer] plug, the rinsing solution comprising hydrogen peroxide.

1 19. (Amended) The method of claim 18, further including polishing the
2 [substrate] metal layer with an abrasive material, wherein the rinsing solution is
3 introduced after a polishing of the substrate.